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What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

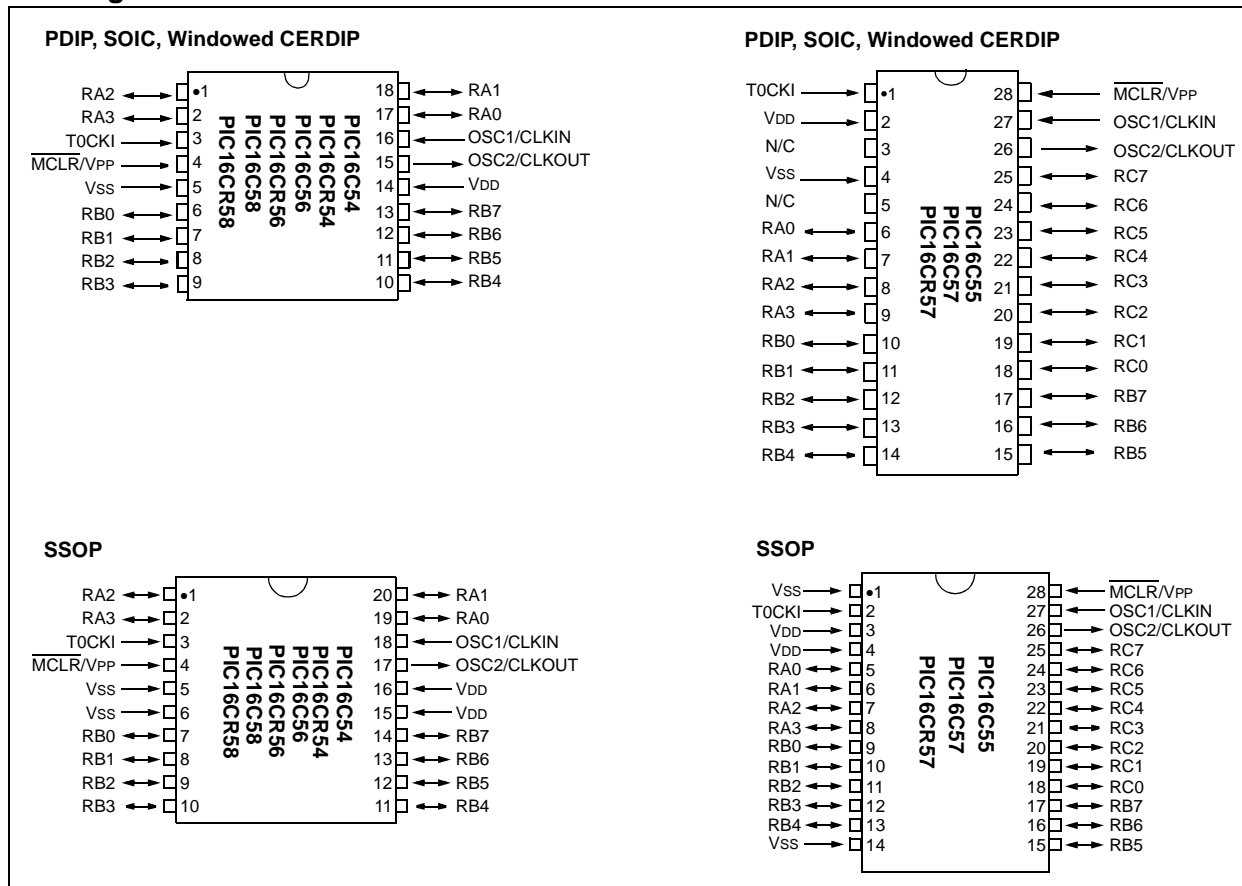
Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	-
Peripherals	POR, WDT
Number of I/O	12
Program Memory Size	768B (512 x 12)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	25 x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	18-DIP (0.300", 7.62mm)
Supplier Device Package	18-PDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16c54a-20i-p

PIC16C5X

Pin Diagrams



Device Differences

Device	Voltage Range	Oscillator Selection (Program)	Oscillator	Process Technology (Microns)	ROM Equivalent	MCLR Filter
PIC16C54	2.5-6.25	Factory	See Note 1	1.2	PIC16CR54A	No
PIC16C54A	2.0-6.25	User	See Note 1	0.9	—	No
PIC16C54C	2.5-5.5	User	See Note 1	0.7	PIC16CR54C	Yes
PIC16C55	2.5-6.25	Factory	See Note 1	1.7	—	No
PIC16C55A	2.5-5.5	User	See Note 1	0.7	—	Yes
PIC16C56	2.5-6.25	Factory	See Note 1	1.7	—	No
PIC16C56A	2.5-5.5	User	See Note 1	0.7	PIC16CR56A	Yes
PIC16C57	2.5-6.25	Factory	See Note 1	1.2	—	No
PIC16C57C	2.5-5.5	User	See Note 1	0.7	PIC16CR57C	Yes
PIC16C58B	2.5-5.5	User	See Note 1	0.7	PIC16CR58B	Yes
PIC16CR54A	2.5-6.25	Factory	See Note 1	1.2	N/A	Yes
PIC16CR54C	2.5-5.5	Factory	See Note 1	0.7	N/A	Yes
PIC16CR56A	2.5-5.5	Factory	See Note 1	0.7	N/A	Yes
PIC16CR57C	2.5-5.5	Factory	See Note 1	0.7	N/A	Yes
PIC16CR58B	2.5-5.5	Factory	See Note 1	0.7	N/A	Yes

Note 1: If you change from this device to another device, please verify oscillator characteristics in your application.

Note: The table shown above shows the generic names of the PIC16C5X devices. For device varieties, please refer to Section 2.0.

PIC16C5X

NOTES:

TABLE 3-1: PINOUT DESCRIPTION - PIC16C54, PIC16CR54, PIC16C56, PIC16CR56, PIC16C58, PIC16CR58

Pin Name	Pin Number			Pin Type	Buffer Type	Description
	DIP	SOIC	SSOP			
RA0	17	17	19	I/O	TTL	Bi-directional I/O port
RA1	18	18	20	I/O	TTL	
RA2	1	1	1	I/O	TTL	
RA3	2	2	2	I/O	TTL	
RB0	6	6	7	I/O	TTL	Bi-directional I/O port
RB1	7	7	8	I/O	TTL	
RB2	8	8	9	I/O	TTL	
RB3	9	9	10	I/O	TTL	
RB4	10	10	11	I/O	TTL	
RB5	11	11	12	I/O	TTL	
RB6	12	12	13	I/O	TTL	
RB7	13	13	14	I/O	TTL	
T0CKI	3	3	3	I	ST	Clock input to Timer0. Must be tied to Vss or VDD, if not in use, to reduce current consumption.
MCLR/VPP	4	4	4	I	ST	Master clear (RESET) input/programming voltage input. This pin is an active low RESET to the device. Voltage on the MCLR/VPP pin must not exceed VDD to avoid unintended entering of Programming mode.
OSC1/CLKIN	16	16	18	I	ST	Oscillator crystal input/external clock source input.
OSC2/CLKOUT	15	15	17	O	—	Oscillator crystal output. Connects to crystal or resonator in crystal Oscillator mode. In RC mode, OSC2 pin outputs CLKOUT, which has 1/4 the frequency of OSC1 and denotes the instruction cycle rate.
VDD	14	14	15,16	P	—	Positive supply for logic and I/O pins.
Vss	5	5	5,6	P	—	Ground reference for logic and I/O pins.

Legend: I = input, O = output, I/O = input/output, P = power, — = Not Used, TTL = TTL input, ST = Schmitt Trigger input

PIC16C5X

TABLE 3-2: PINOUT DESCRIPTION - PIC16C55, PIC16C57, PIC16CR57

Pin Name	Pin Number			Pin Type	Buffer Type	Description
	DIP	SOIC	SSOP			
RA0	6	6	5	I/O	TTL	Bi-directional I/O port
RA1	7	7	6	I/O	TTL	
RA2	8	8	7	I/O	TTL	
RA3	9	9	8	I/O	TTL	
RB0	10	10	9	I/O	TTL	Bi-directional I/O port
RB1	11	11	10	I/O	TTL	
RB2	12	12	11	I/O	TTL	
RB3	13	13	12	I/O	TTL	
RB4	14	14	13	I/O	TTL	
RB5	15	15	15	I/O	TTL	
RB6	16	16	16	I/O	TTL	
RB7	17	17	17	I/O	TTL	
RC0	18	18	18	I/O	TTL	Bi-directional I/O port
RC1	19	19	19	I/O	TTL	
RC2	20	20	20	I/O	TTL	
RC3	21	21	21	I/O	TTL	
RC4	22	22	22	I/O	TTL	
RC5	23	23	23	I/O	TTL	
RC6	24	24	24	I/O	TTL	
RC7	25	25	25	I/O	TTL	
T0CKI	1	1	2	I	ST	Clock input to Timer0. Must be tied to Vss or VDD, if not in use, to reduce current consumption.
$\overline{\text{MCLR}}$	28	28	28	I	ST	Master clear (RESET) input. This pin is an active low RESET to the device.
OSC1/CLKIN	27	27	27	I	ST	Oscillator crystal input/external clock source input.
OSC2/CLKOUT	26	26	26	O	—	Oscillator crystal output. Connects to crystal or resonator in crystal Oscillator mode. In RC mode, OSC2 pin outputs CLKOUT which has 1/4 the frequency of OSC1, and denotes the instruction cycle rate.
VDD	2	2	3,4	P	—	Positive supply for logic and I/O pins.
Vss	4	4	1,14	P	—	Ground reference for logic and I/O pins.
N/C	3,5	3,5	—	—	—	Unused, do not connect.

Legend: I = input, O = output, I/O = input/output, P = power, — = Not Used, TTL = TTL input, ST = Schmitt Trigger input

4.3 External Crystal Oscillator Circuit

Either a prepackaged oscillator or a simple oscillator circuit with TTL gates can be used as an external crystal oscillator circuit. Prepackaged oscillators provide a wide operating range and better stability. A well-designed crystal oscillator will provide good performance with TTL gates. Two types of crystal oscillator circuits can be used: one with parallel resonance, or one with series resonance.

Figure 4-3 shows an implementation example of a parallel resonant oscillator circuit. The circuit is designed to use the fundamental frequency of the crystal. The 74AS04 inverter performs the 180-degree phase shift that a parallel oscillator requires. The 4.7 k Ω resistor provides the negative feedback for stability. The 10 k Ω potentiometers bias the 74AS04 in the linear region. This circuit could be used for external oscillator designs.

FIGURE 4-3: EXAMPLE OF EXTERNAL PARALLEL RESONANT CRYSTAL OSCILLATOR CIRCUIT (USING XT, HS OR LP OSCILLATOR MODE)

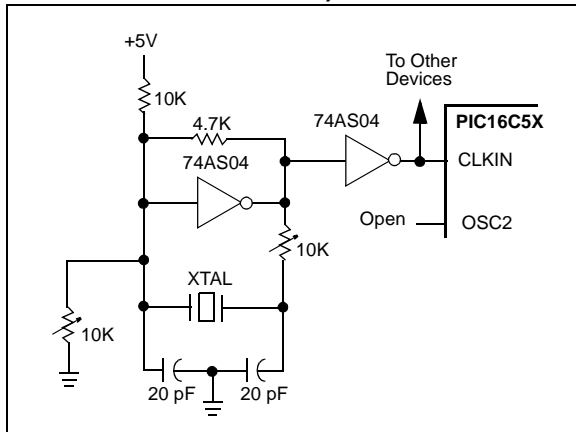
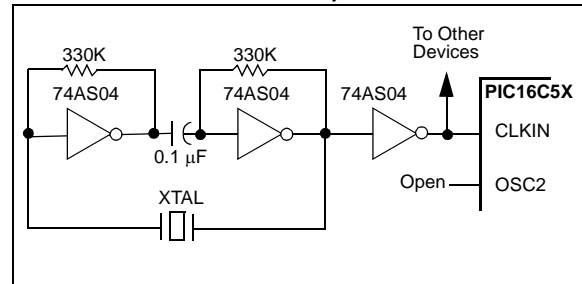


Figure 4-4 shows a series resonant oscillator circuit. This circuit is also designed to use the fundamental frequency of the crystal. The inverter performs a 180-degree phase shift in a series resonant oscillator circuit. The 330 k Ω resistors provide the negative feedback to bias the inverters in their linear region.

FIGURE 4-4: EXAMPLE OF EXTERNAL SERIES RESONANT CRYSTAL OSCILLATOR CIRCUIT (USING XT, HS OR LP OSCILLATOR MODE)



8.0 TIMER0 MODULE AND TMRO REGISTER

The Timer0 module has the following features:

- 8-bit timer/counter register, TMR0
 - Readable and writable
- 8-bit software programmable prescaler
- Internal or external clock select
 - Edge select for external clock

Figure 8-1 is a simplified block diagram of the Timer0 module, while Figure 8-2 shows the electrical structure of the Timer0 input.

Timer mode is selected by clearing the T0CS bit (OPTION<5>). In Timer mode, the Timer0 module will increment every instruction cycle (without prescaler). If TMR0 register is written, the increment is inhibited for the following two cycles (Figure 8-3 and Figure 8-4). The user can work around this by writing an adjusted value to the TMR0 register.

Counter mode is selected by setting the T0CS bit (OPTION<5>). In this mode, Timer0 will increment either on every rising or falling edge of pin T0CKI. The incrementing edge is determined by the source edge select bit T0SE (OPTION<4>). Clearing the T0SE bit selects the rising edge. Restrictions on the external clock input are discussed in detail in Section 8.1.

Note: The prescaler may be used by either the Timer0 module or the Watchdog Timer, but not both.

The prescaler assignment is controlled in software by the control bit PSA (OPTION<3>). Clearing the PSA bit will assign the prescaler to Timer0. The prescaler is not readable or writable. When the prescaler is assigned to the Timer0 module, prescale values of 1:2, 1:4,..., 1:256 are selectable. Section 8.2 details the operation of the prescaler.

A summary of registers associated with the Timer0 module is found in Table 8-1.

FIGURE 8-1: TIMER0 BLOCK DIAGRAM

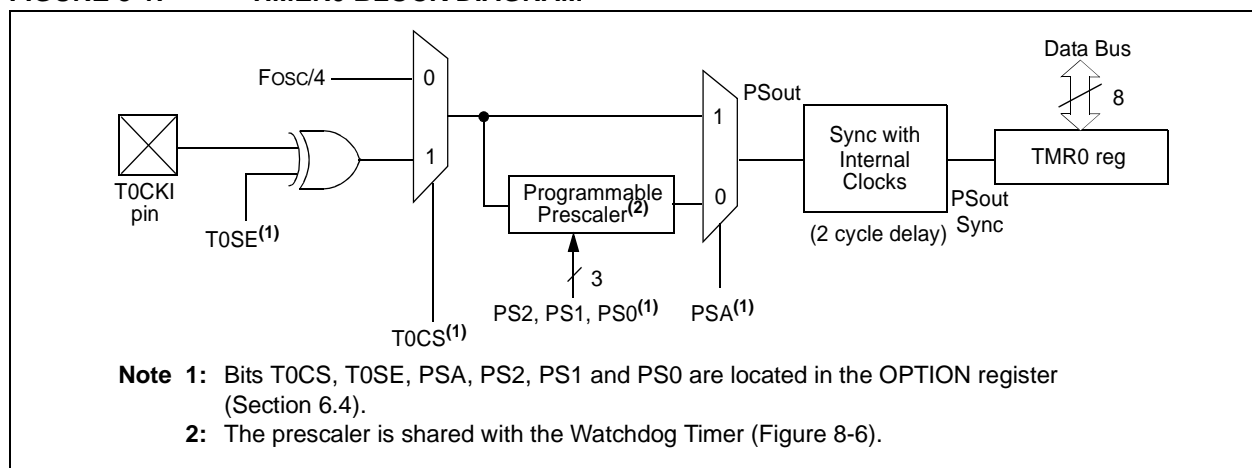
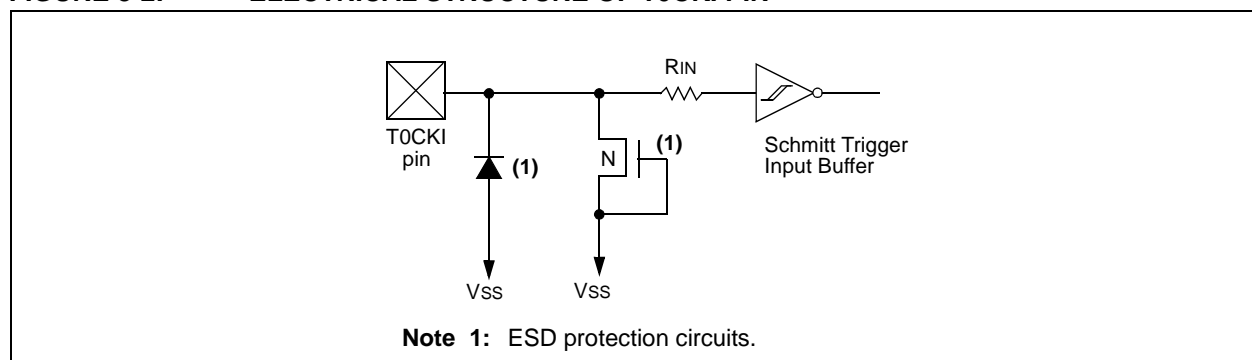


FIGURE 8-2: ELECTRICAL STRUCTURE OF T0CKI PIN



8.1 Using Timer0 with an External Clock

When an external clock input is used for Timer0, it must meet certain requirements. The external clock requirement is due to internal phase clock (Tosc) synchronization. Also, there is a delay in the actual incrementing of Timer0 after synchronization.

8.1.1 EXTERNAL CLOCK SYNCHRONIZATION

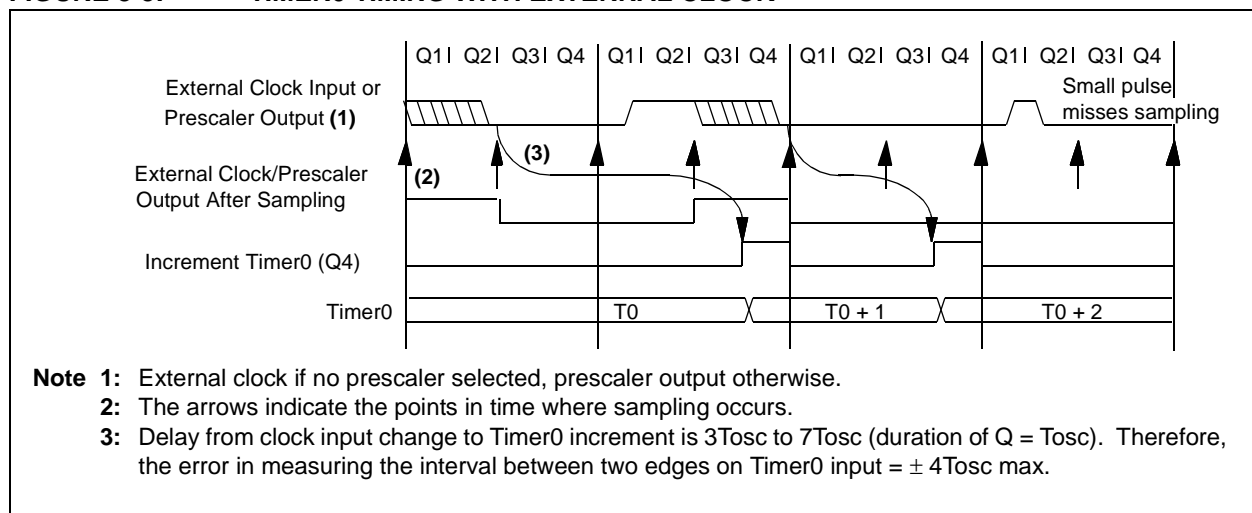
When no prescaler is used, the external clock input is the same as the prescaler output. The synchronization of T0CKI with the internal phase clocks is accomplished by sampling the prescaler output on the Q2 and Q4 cycles of the internal phase clocks (Figure 8-5). Therefore, it is necessary for T0CKI to be high for at least 2Tosc (and a small RC delay of 20 ns) and low for at least 2Tosc (and a small RC delay of 20 ns). Refer to the electrical specification of the desired device.

When a prescaler is used, the external clock input is divided by the asynchronous ripple counter-type prescaler so that the prescaler output is symmetrical. For the external clock to meet the sampling requirement, the ripple counter must be taken into account. Therefore, it is necessary for T0CKI to have a period of at least 4Tosc (and a small RC delay of 40 ns) divided by the prescaler value. The only requirement on T0CKI high and low time is that they do not violate the minimum pulse width requirement of 10 ns. Refer to parameters 40, 41 and 42 in the electrical specification of the desired device.

8.1.2 TIMER0 INCREMENT DELAY

Since the prescaler output is synchronized with the internal clocks, there is a small delay from the time the external clock edge occurs to the time the Timer0 module is actually incremented. Figure 8-5 shows the delay from the external clock edge to the timer incrementing.

FIGURE 8-5: TIMER0 TIMING WITH EXTERNAL CLOCK



11.0 DEVELOPMENT SUPPORT

The PIC® microcontrollers are supported with a full range of hardware and software development tools:

- Integrated Development Environment
 - MPLAB® IDE Software
- Assemblers/Compilers/Linkers
 - MPASM™ Assembler
 - MPLAB C17 and MPLAB C18 C Compilers
 - MPLINK™ Object Linker/
MPLIB™ Object Librarian
- Simulators
 - MPLAB SIM Software Simulator
- Emulators
 - MPLAB ICE 2000 In-Circuit Emulator
 - ICEPIC™ In-Circuit Emulator
- In-Circuit Debugger
 - MPLAB ICD
- Device Programmers
 - PRO MATE® II Universal Device Programmer
 - PICSTART® Plus Entry-Level Development Programmer
- Low Cost Demonstration Boards
 - PICDEM™ 1 Demonstration Board
 - PICDEM 2 Demonstration Board
 - PICDEM 3 Demonstration Board
 - PICDEM 17 Demonstration Board
 - KEELQ® Demonstration Board

11.1 MPLAB Integrated Development Environment Software

The MPLAB IDE software brings an ease of software development previously unseen in the 8-bit microcontroller market. The MPLAB IDE is a Windows®-based application that contains:

- An interface to debugging tools
 - simulator
 - programmer (sold separately)
 - emulator (sold separately)
 - in-circuit debugger (sold separately)
- A full-featured editor
- A project manager
- Customizable toolbar and key mapping
- A status bar
- On-line help

The MPLAB IDE allows you to:

- Edit your source files (either assembly or 'C')
- One touch assemble (or compile) and download to PIC MCU emulator and simulator tools (automatically updates all project information)
- Debug using:
 - source files
 - absolute listing file
 - machine code

The ability to use MPLAB IDE with multiple debugging tools allows users to easily switch from the cost-effective simulator to a full-featured emulator with minimal retraining.

11.2 MPASM Assembler

The MPASM assembler is a full-featured universal macro assembler for all PIC MCUs.

The MPASM assembler has a command line interface and a Windows shell. It can be used as a stand-alone application on a Windows 3.x or greater system, or it can be used through MPLAB IDE. The MPASM assembler generates relocatable object files for the MPLINK object linker, Intel® standard HEX files, MAP files to detail memory usage and symbol reference, an absolute LST file that contains source lines and generated machine code, and a COD file for debugging.

The MPASM assembler features include:

- Integration into MPLAB IDE projects.
- User-defined macros to streamline assembly code.
- Conditional assembly for multi-purpose source files.
- Directives that allow complete control over the assembly process.

11.3 MPLAB C17 and MPLAB C18 C Compilers

The MPLAB C17 and MPLAB C18 Code Development Systems are complete ANSI 'C' compilers for Microchip's PIC17CXXX and PIC18CXXX family of microcontrollers, respectively. These compilers provide powerful integration capabilities and ease of use not found with other compilers.

For easier source level debugging, the compilers provide symbol information that is compatible with the MPLAB IDE memory display.

PIC16C5X

NOTES:

TABLE 13-1: EXTERNAL CLOCK TIMING REQUIREMENTS - PIC16CR54A

Standard Operating Conditions (unless otherwise specified) Operating Temperature $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ for commercial $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended							
Param No.	Symbol	Characteristic	Min	Typ†	Max	Units	Conditions
1	Tosc	External CLKIN Period ⁽¹⁾	250	—	—	ns	XT osc mode
			250	—	—	ns	HS osc mode (04)
			100	—	—	ns	HS osc mode (10)
			50	—	—	ns	HS osc mode (20)
			5.0	—	—	μs	LP osc mode
		Oscillator Period ⁽¹⁾	250	—	—	ns	RC osc mode
			250	—	10,000	ns	XT osc mode
			250	—	250	ns	HS osc mode (04)
			100	—	250	ns	HS osc mode (10)
			50	—	250	ns	HS osc mode (20)
			5.0	—	200	μs	LP osc mode
2	Tcy	Instruction Cycle Time ⁽²⁾	—	4/Fosc	—	—	
3	TosL, TosH	Clock in (OSC1) Low or High Time	50*	—	—	ns	XT oscillator
			20*	—	—	ns	HS oscillator
			2.0*	—	—	μs	LP oscillator
4	TosR, TosF	Clock in (OSC1) Rise or Fall Time	—	—	25*	ns	XT oscillator
			—	—	25*	ns	HS oscillator
			—	—	50*	ns	LP oscillator

* These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption.

When an external clock input is used, the "max" cycle time limit is "DC" (no clock) for all devices.

2: Instruction cycle period (TCY) equals four times the input oscillator time base period.

FIGURE 13-4: RESET, WATCHDOG TIMER, AND DEVICE RESET TIMER TIMING - PIC16CR54A

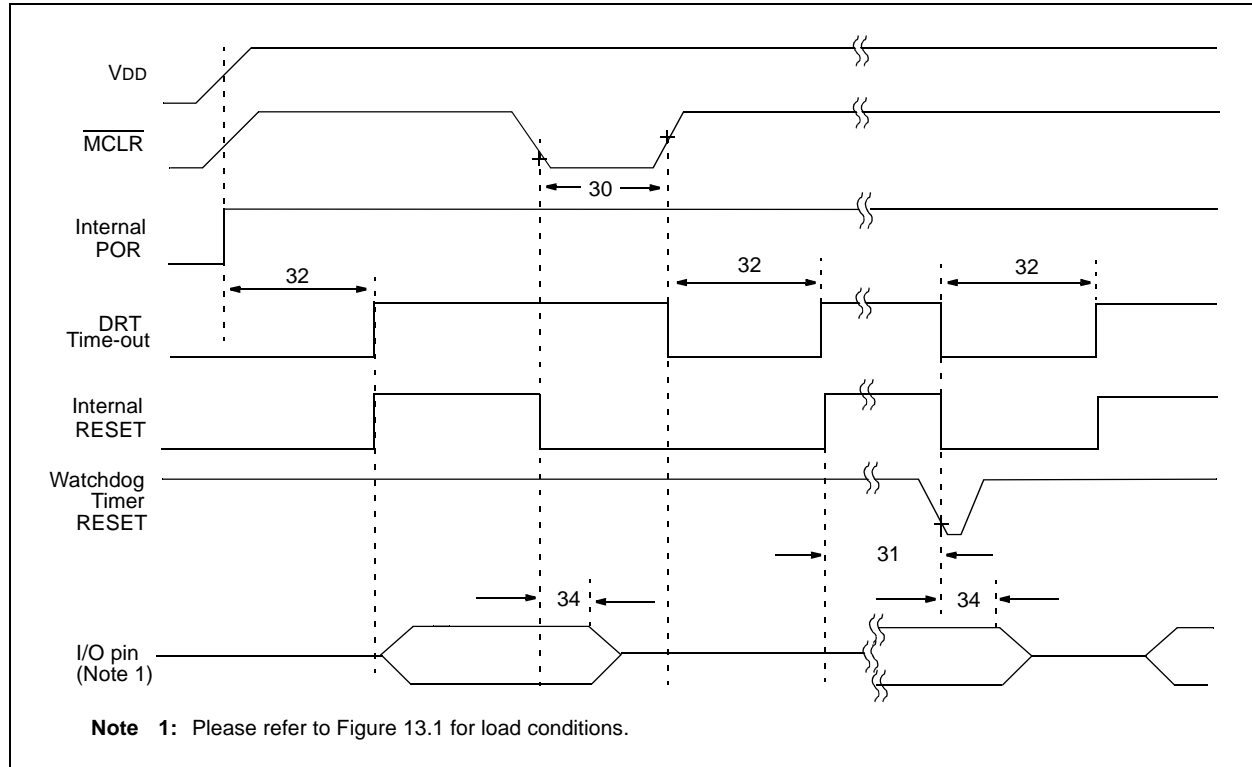


TABLE 13-3: RESET, WATCHDOG TIMER, AND DEVICE RESET TIMER - PIC16CR54A

Standard Operating Conditions (unless otherwise specified)							
AC Characteristics		Operating Temperature					
		0°C ≤ TA ≤ +70°C for commercial					
		-40°C ≤ TA ≤ +85°C for industrial					
		-40°C ≤ TA ≤ +125°C for extended					
Param No.	Symbol	Characteristic	Min	Typ†	Max	Units	Conditions
30	TmCL	MCLR Pulse Width (low)	1.0*	—	—	μs	VDD = 5.0V
31	Twdt	Watchdog Timer Time-out Period (No Prescaler)	7.0*	18*	40*	ms	VDD = 5.0V (Comm)
32	TDRT	Device Reset Timer Period	7.0*	18*	30*	ms	VDD = 5.0V (Comm)
34	TioZ	I/O Hi-impedance from MCLR Low	—	—	1.0*	μs	

* These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 14-21: PORTA, B AND C IoL vs. VOL, VDD = 3 V

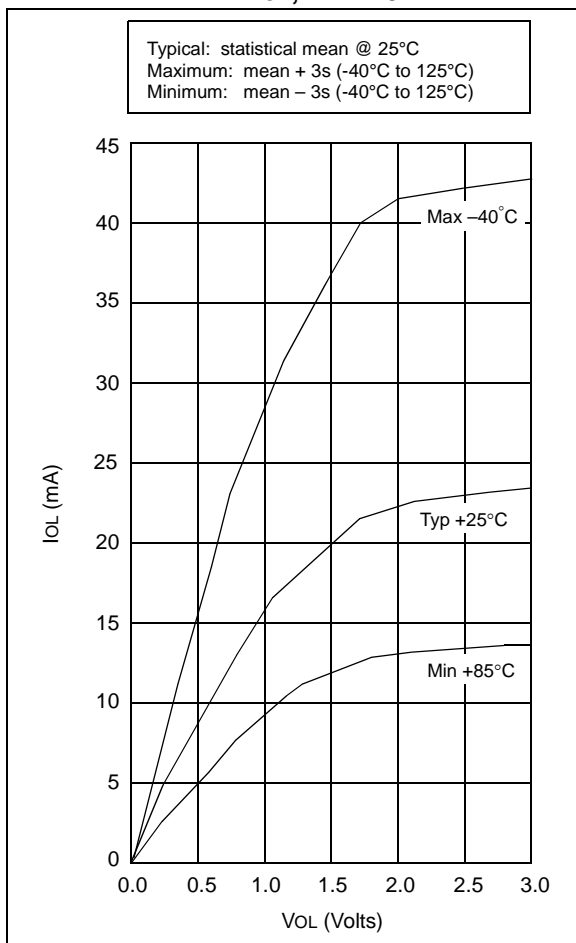


FIGURE 14-22: PORTA, B AND C IoL vs. VOL, VDD = 5 V

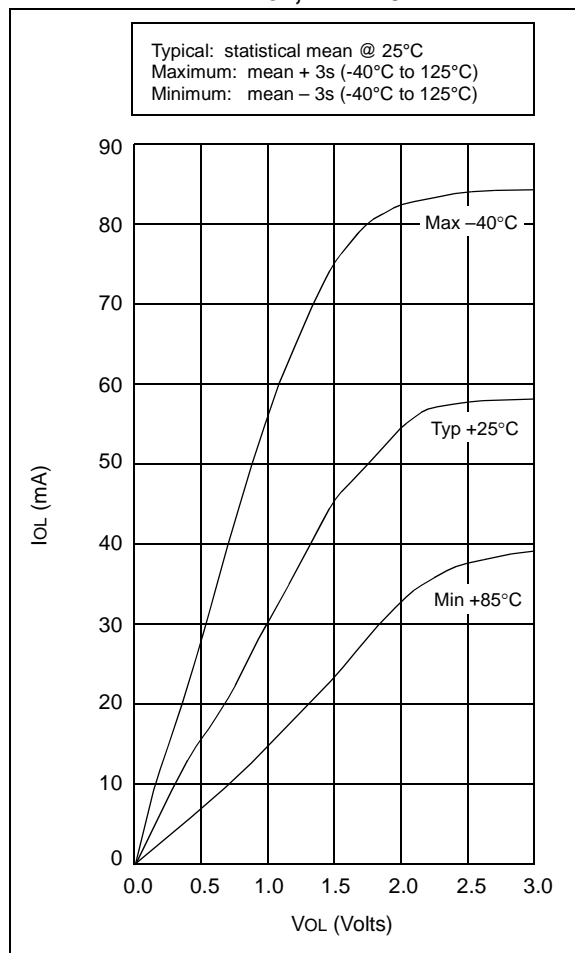


FIGURE 16-10: TYPICAL I_{DD} vs. FREQUENCY (WDT DISABLED, RC MODE @ 20 pF, 25°C)

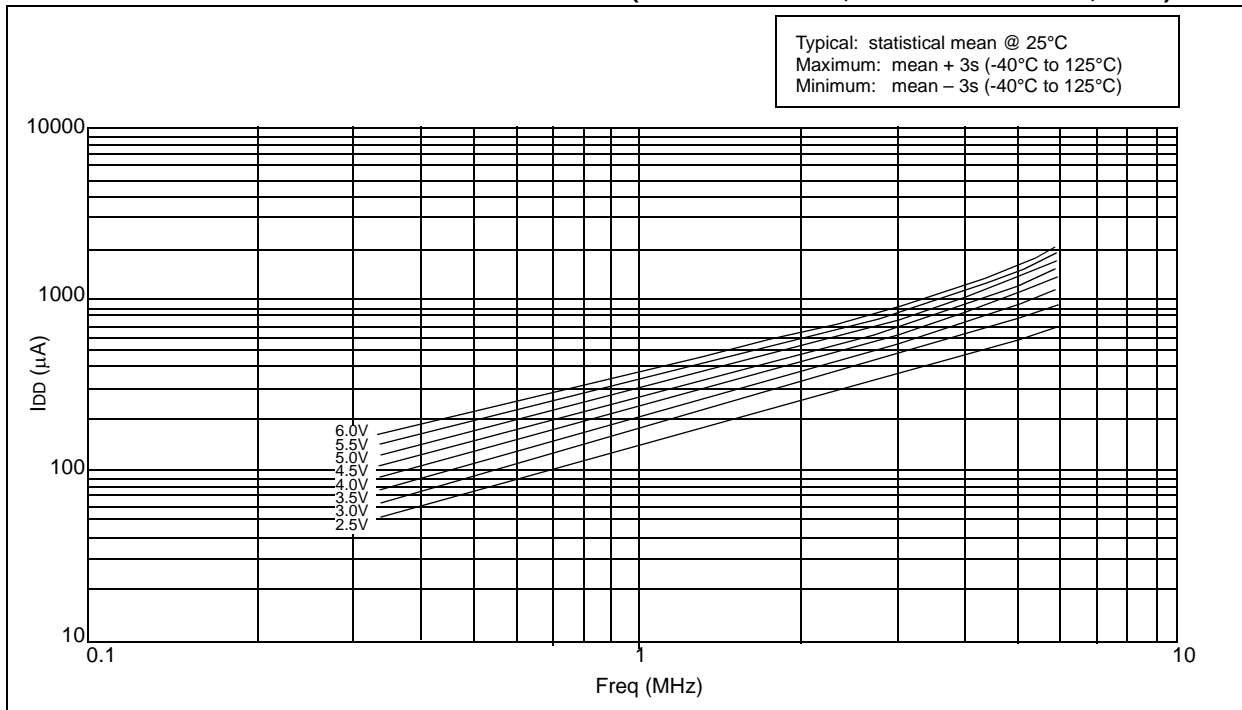


FIGURE 16-11: MAXIMUM I_{DD} vs. FREQUENCY (WDT DISABLED, RC MODE @ 20 pF, -40°C to +85°C)

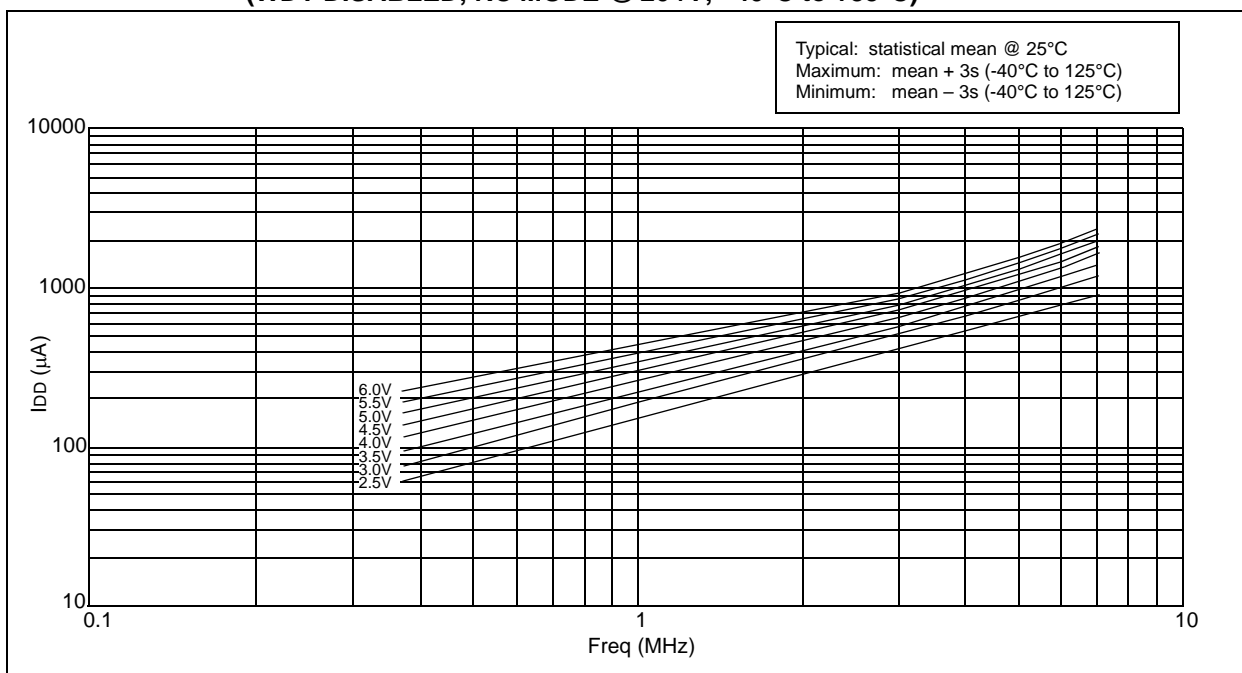


FIGURE 16-16: WDT TIMER TIME-OUT PERIOD vs. VDD⁽¹⁾

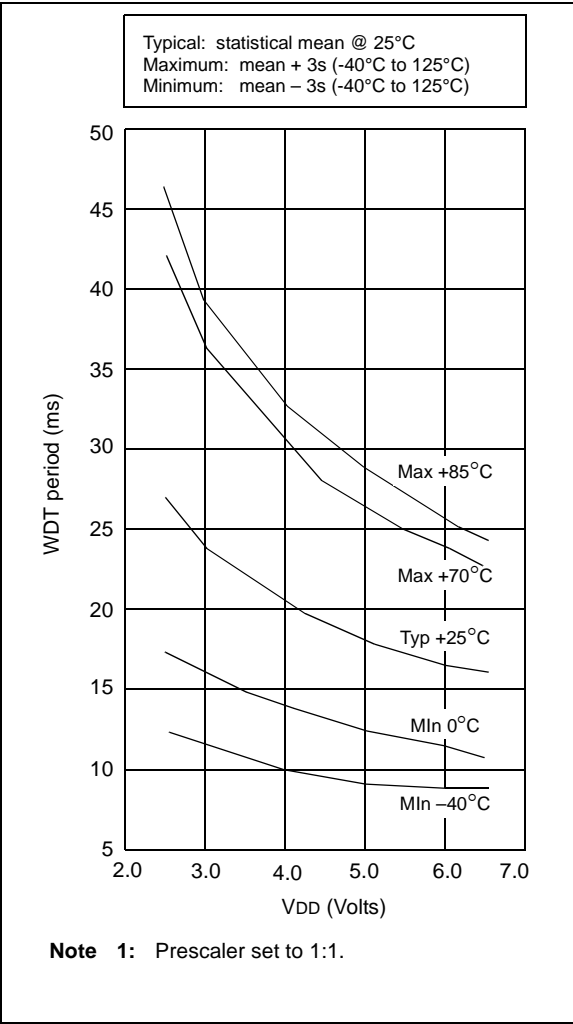


FIGURE 16-17: TRANSCONDUCTANCE (gm) OF HS OSCILLATOR vs. VDD

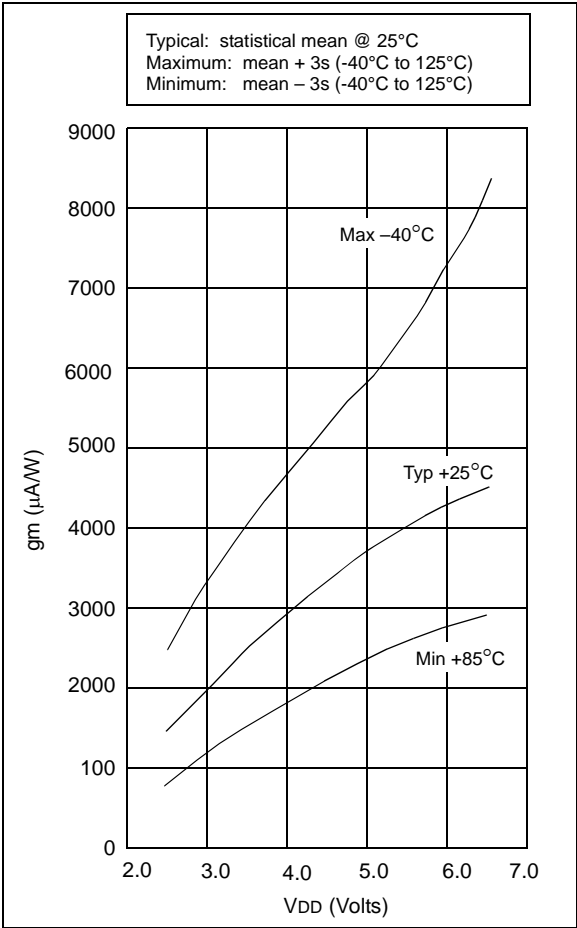


FIGURE 16-22: PORTA, B AND C IoL vs. VOL, VDD = 3V

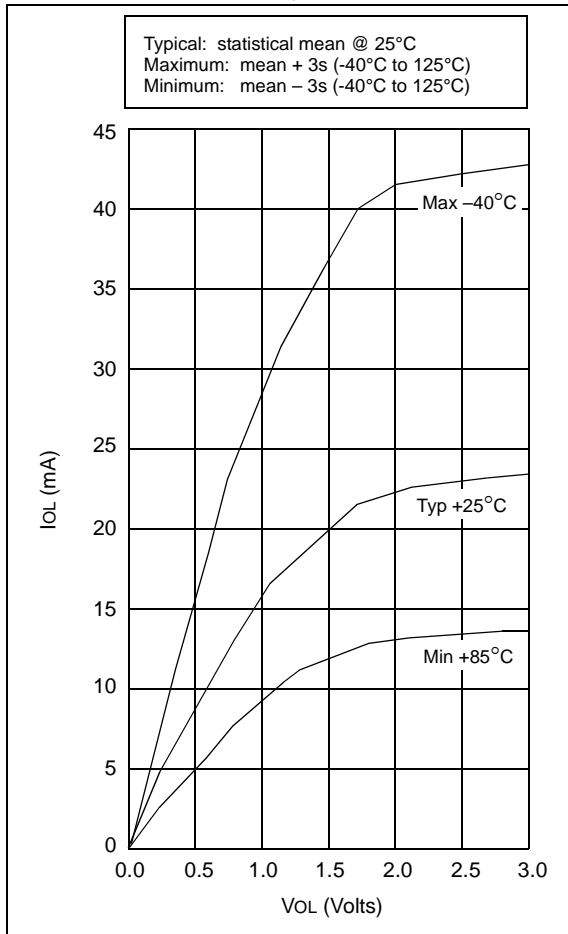


FIGURE 16-23: PORTA, B AND C IoL vs. VOL, VDD = 5V

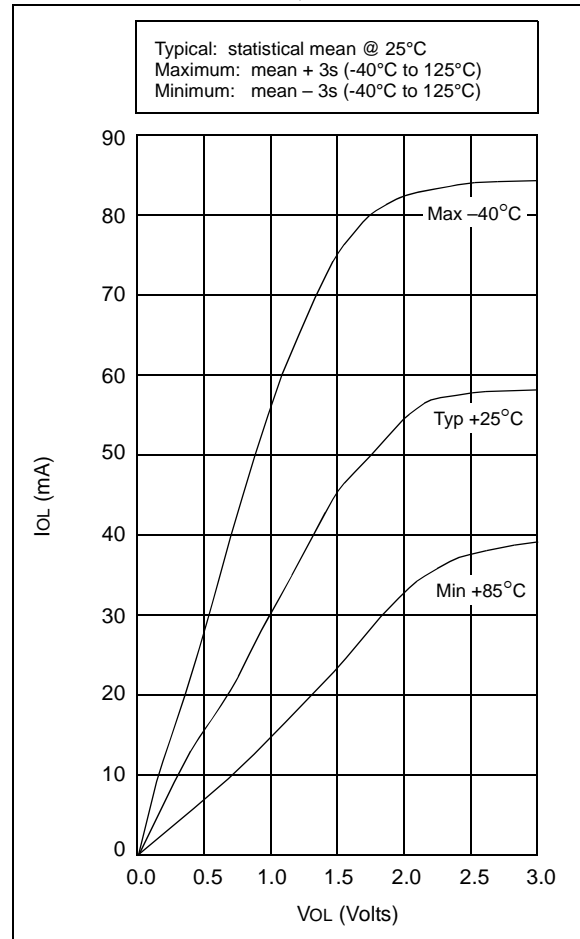


TABLE 16-2: INPUT CAPACITANCE FOR PIC16C54A/C58A

Pin	Typical Capacitance (pF)	
	18L PDIP	18L SOIC
RA port	5.0	4.3
RB port	5.0	4.3
MCLR	17.0	17.0
OSC1	4.0	3.5
OSC2/CLKOUT	4.3	3.5
T0CKI	3.2	2.8

All capacitance values are typical at 25°C. A part-to-part variation of $\pm 25\%$ (three standard deviations) should be taken into account.

PIC16C5X

FIGURE 17-7: CLKOUT AND I/O TIMING - PIC16C5X, PIC16CR5X

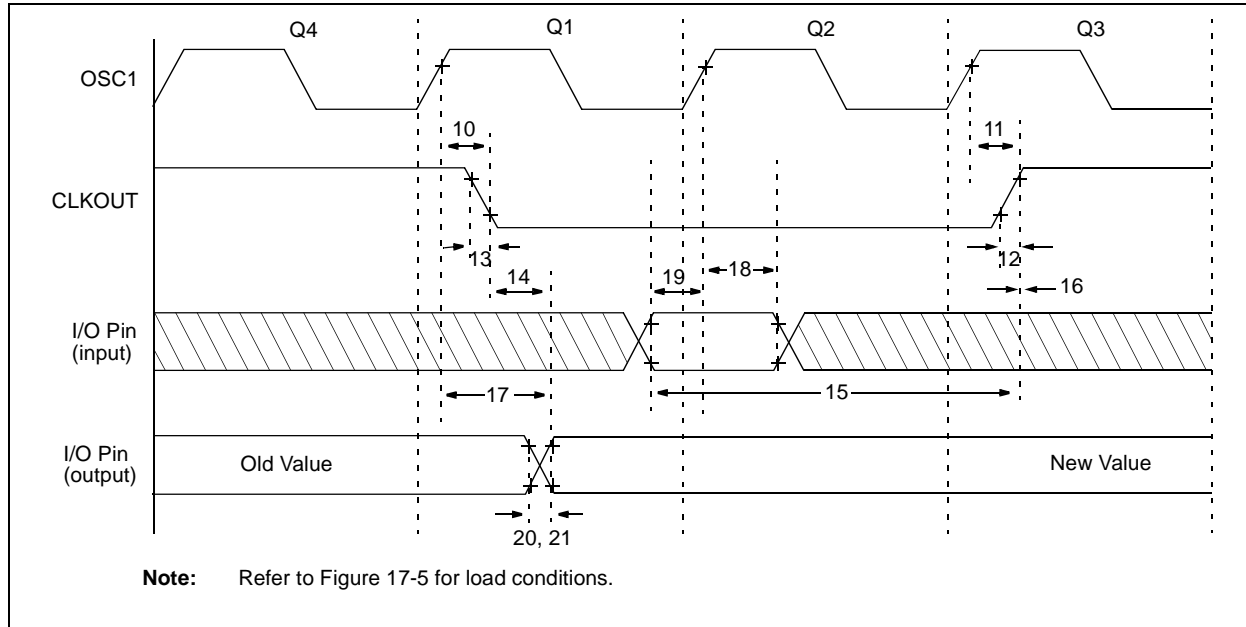


TABLE 17-2: CLKOUT AND I/O TIMING REQUIREMENTS - PIC16C5X, PIC16CR5X

AC Characteristics		Standard Operating Conditions (unless otherwise specified)				
		Operating Temperature				
		0°C ≤ TA ≤ +70°C for commercial				
		-40°C ≤ TA ≤ +85°C for industrial				
		-40°C ≤ TA ≤ +125°C for extended				
Param No.	Symbol	Characteristic	Min	Typ†	Max	Units
10	TosH2ckL	OSC1↑ to CLKOUT↓ ⁽¹⁾	—	15	30**	ns
11	TosH2ckH	OSC1↑ to CLKOUT↑ ⁽¹⁾	—	15	30**	ns
12	TckR	CLKOUT rise time ⁽¹⁾	—	5.0	15**	ns
13	TckF	CLKOUT fall time ⁽¹⁾	—	5.0	15**	ns
14	TckL2ioV	CLKOUT↓ to Port out valid ⁽¹⁾	—	—	40**	ns
15	TioV2ckH	Port in valid before CLKOUT↑ ⁽¹⁾	0.25 TCY+30*	—	—	ns
16	TckH2ioI	Port in hold after CLKOUT↑ ⁽¹⁾	0*	—	—	ns
17	TosH2ioV	OSC1↑ (Q1 cycle) to Port out valid ⁽²⁾	—	—	100*	ns
18	TosH2ioI	OSC1↑ (Q2 cycle) to Port input invalid (I/O in hold time)	TBD	—	—	ns
19	TioV2osH	Port input valid to OSC1↑ (I/O in setup time)	TBD	—	—	ns
20	TioR	Port output rise time ⁽²⁾	—	10	25**	ns
21	TioF	Port output fall time ⁽²⁾	—	10	25**	ns

* These parameters are characterized but not tested.

** These parameters are design targets and are not tested. No characterization data available at this time.

† Data in the Typical ("Typ") column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Measurements are taken in RC Mode where CLKOUT output is 4 x TOSC.

2: Refer to Figure 17-5 for load conditions.

FIGURE 18-4: TYPICAL RC OSCILLATOR FREQUENCY vs. V_{DD} , $C_{EXT} = 300$ pF, 25°C

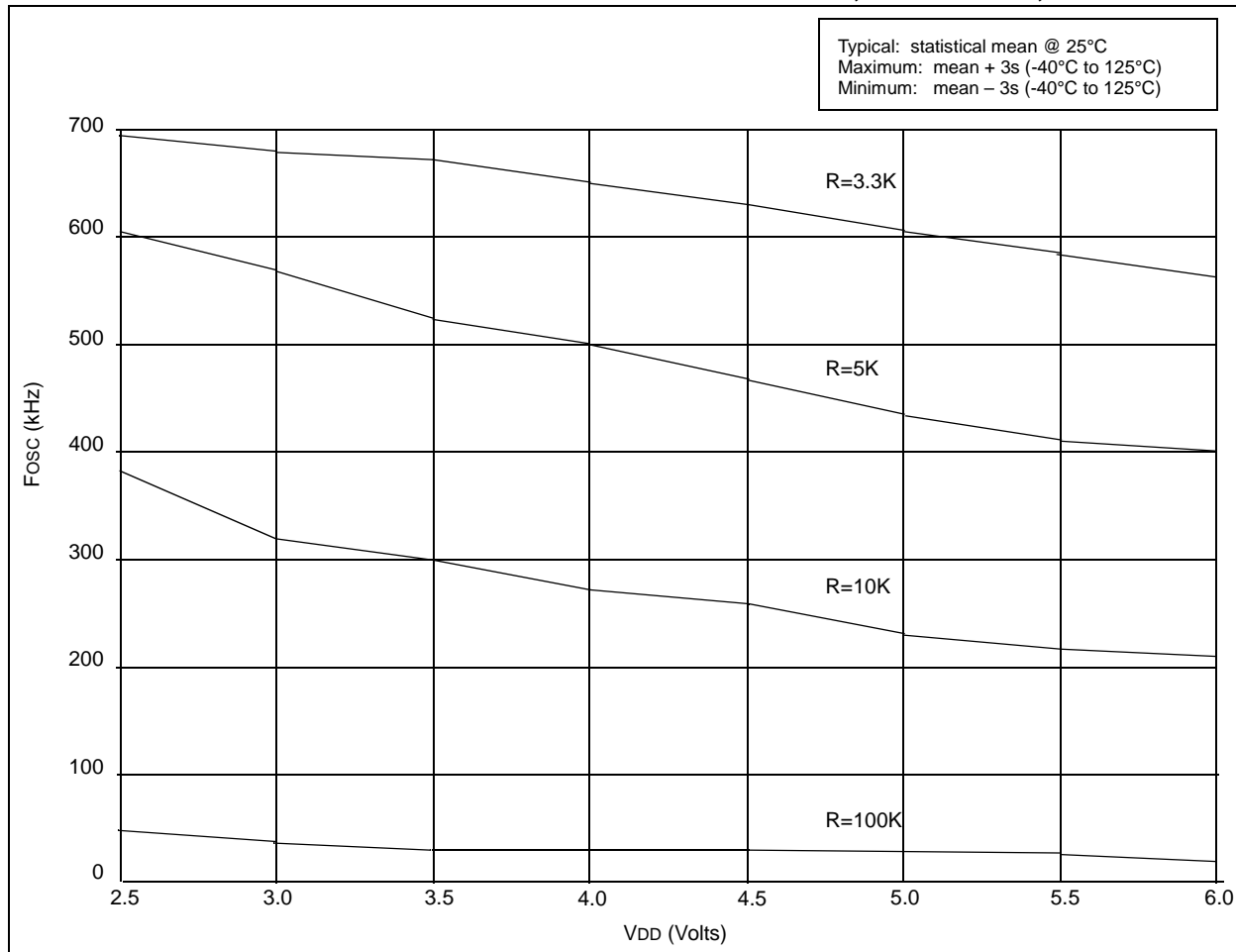
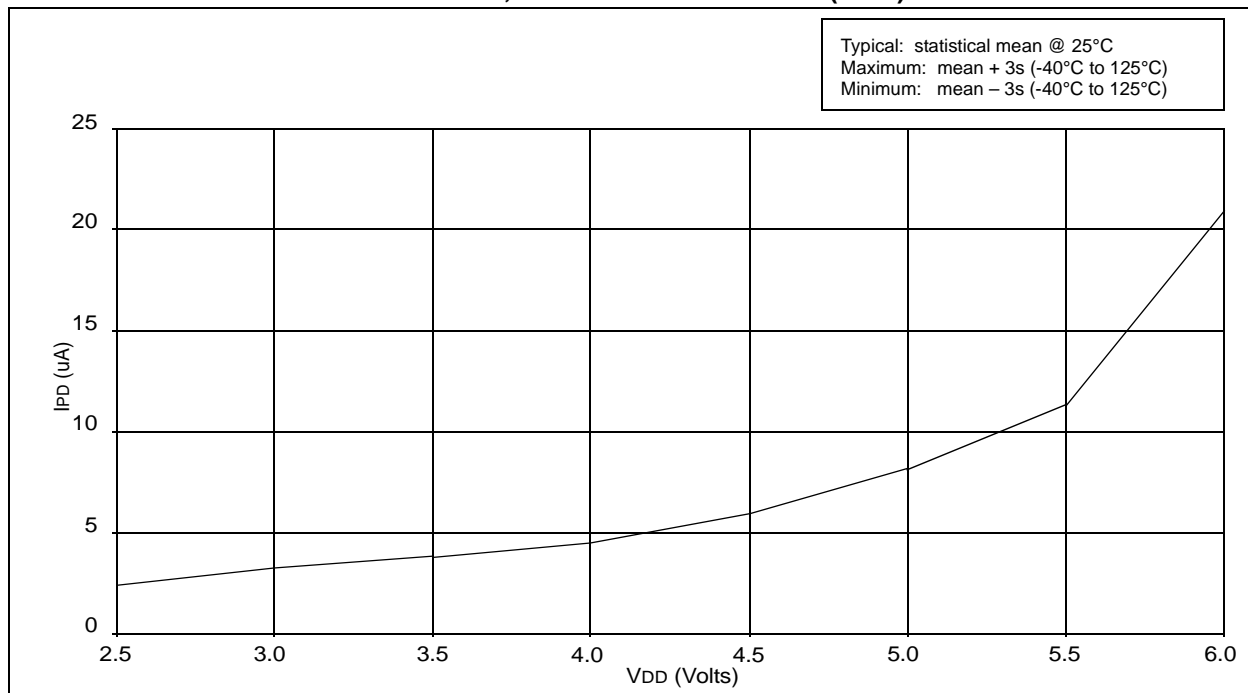


FIGURE 18-5: TYPICAL I_{PD} vs. V_{DD} , WATCHDOG DISABLED (25°C)



PIC16C5X

FIGURE 19-5: RESET, WATCHDOG TIMER, AND DEVICE RESET TIMER TIMING - PIC16C5X-40

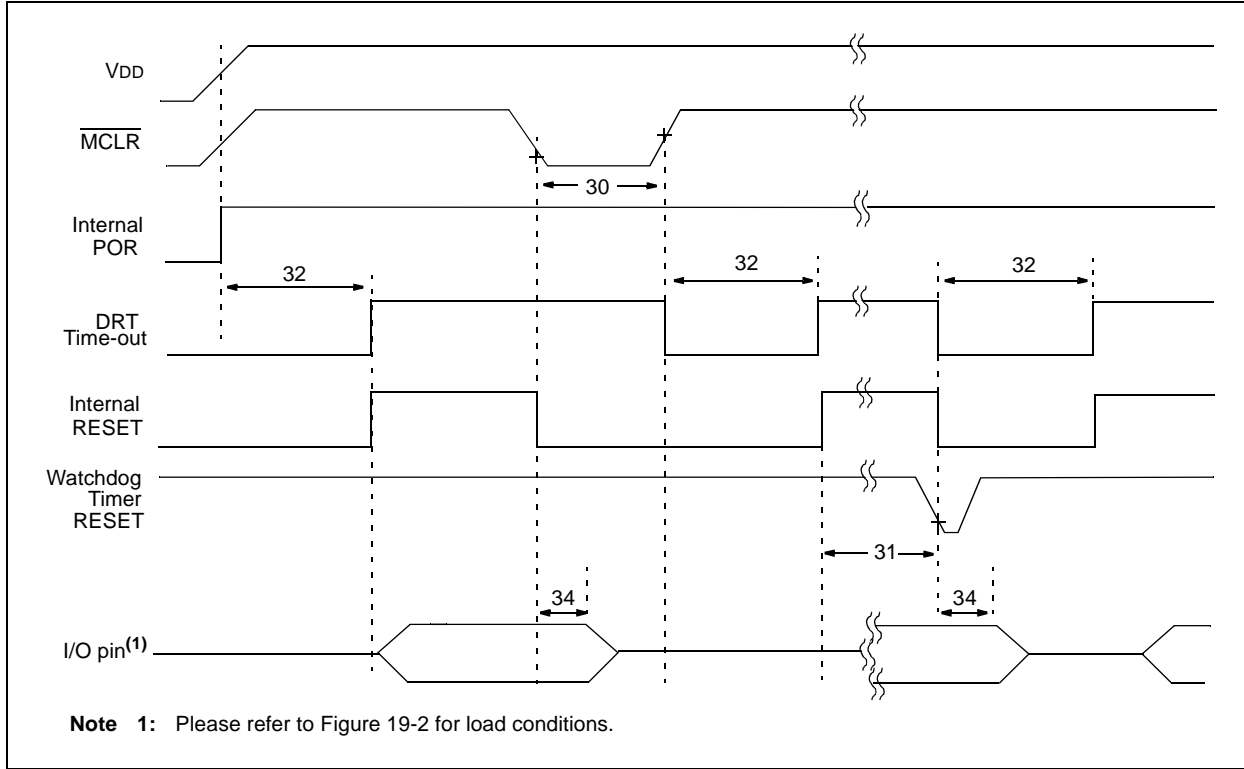


TABLE 19-3: RESET, WATCHDOG TIMER, AND DEVICE RESET TIMER - PIC16C5X-40

Standard Operating Conditions (unless otherwise specified)							
AC Characteristics							
Operating Temperature $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ (commercial)							
Operating Voltage VDD range is described in Section 19.1.							
Param No.	Symbol	Characteristic	Min	Typ†	Max	Units	Conditions
30	Tmcl	MCLR Pulse Width (low)	1000*	—	—	ns	VDD = 5.0V
31	Twdt	Watchdog Timer Time-out Period (No Prescaler)	9.0*	18*	30*	ms	VDD = 5.0V (Comm)
32	TDRT	Device Reset Timer Period	9.0*	18*	30*	ms	VDD = 5.0V (Comm)
34	Tioz	I/O Hi-impedance from MCLR Low	100*	300*	1000*	ns	

* These parameters are characterized but not tested.

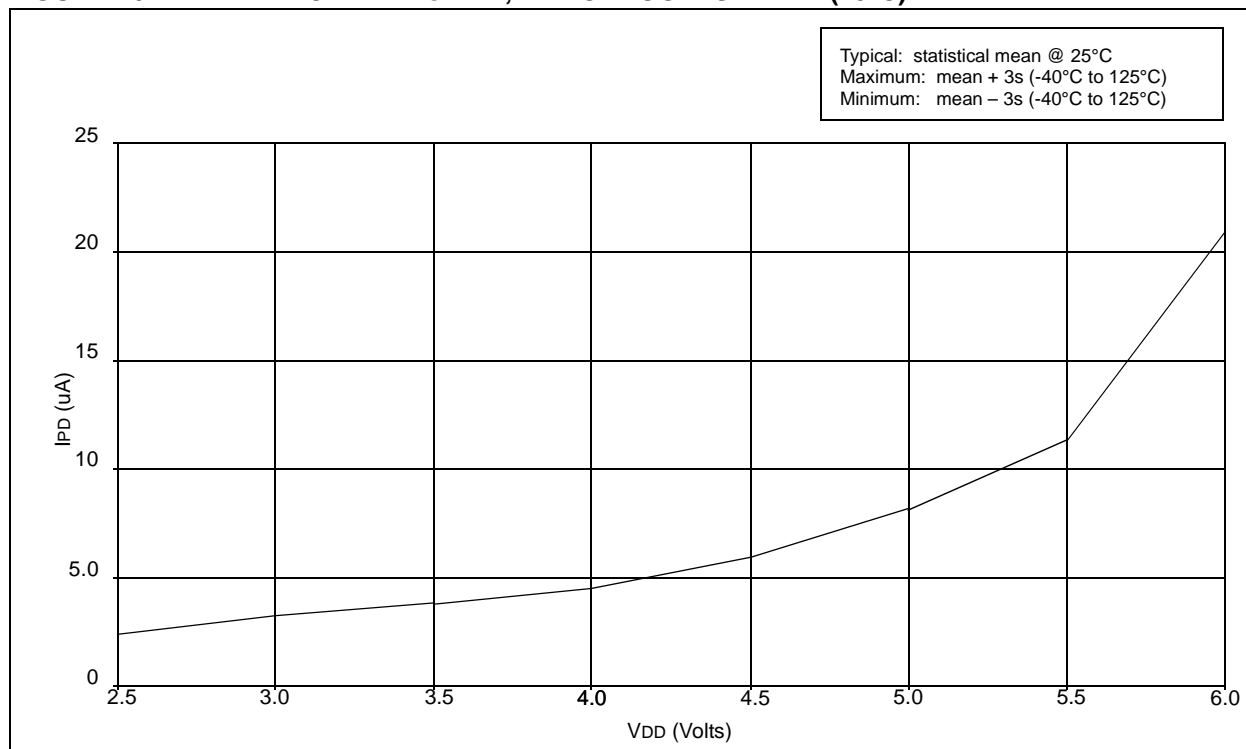
† Data in the Typical ("Typ") column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

20.0 DEVICE CHARACTERIZATION - PIC16LC54C 40MHz

The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.

“Typical” represents the mean of the distribution at 25°C. “Maximum” or “minimum” represents (mean + 3 σ) or (mean – 3 σ) respectively, where σ is a standard deviation, over the whole temperature range.

FIGURE 20-1: TYPICAL I_{PD} vs. V_{DD} , WATCHDOG DISABLED (25°C)



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